

L I M I T E D T E N D E R
N O T I C E

Tender Ref. No. PUR-12/59/2021-MCAD_DIV_SAM_CHE-SMR CHE DEPTT - 12580 Date 25-10-2021 Tender Due Date 09-11-2021

To


Dear Sir,

The Purchase Officer, SAMEER-Centre for Electromagnetics invites sealed tender for the supply of materials / Services as per details given below:

Sl. No	Description of Items	(as per the specification enclosed)	Qty(Nos.)
1.	PCB Fabrication – 8 Layer board on Rogers substrate		10
2.	Components assembly		10

Terms and Conditions:

1. Tenders to be submitted to The Purchase Officer ,SAMEER-CEM ,CIT Campus, 2nd Cross Road, Taramani, Chennai 600 113.
2. Delivery / Completion period should be clearly indicated.
3. Excise Duty, GST Percentage should be clearly indicated if admissible. Not eligible for FORM 'C' /'D'
4. WE ARE EXEMPTED FROM EXCISE DUTY
5. Quotation should be valid for atleast 60 days from the date of opening of the tender
6. Quotation should be sent in sealed envelope super scribing the tender reference number and tender due date. E-mail quotation will not be accepted. YOUR OFFER WILL NOT BE CONSIDERED IF OUR TENDER REFERENCE NO. & TENDER DUE DATE IS NOT MENTIONED ON COVER.
7. Late tenders will not be accepted under any circumstances
8. We reserve the right to accept or reject any quotations fully or partly without assigning any reasons.
9. For Further Clarification Please Contact 044-22544061 / 22544020 Email: purchase.chn.sameer@nic.in
10. Unsolicited bids shall not be considered


25/10/2021
(P. Ramamoorthi)
Head – Administration

Contd...,



CIT Campus, 2nd Cross Road, Taramani, Chennai - 600 113, India

सी.आई.टी.परीसर, दूसरा क्रॉस रोड, तारामनी चेन्नै - ६०० ११३.

दूरभाषिन : Tel : +91-44-22541583 / 1817 / 2106 / 2452 फैक्स / Fax : 2254 1938 / 1424

वेबसाईट : www.sameer.org.in

SPECIFICATION LIST

S.No	REQUIREMENTS	VALUE
1	Board Thickness	1.533 mm
2	Via Requirements	
	a.Through hole	Yes
	b.Blind via	Yes
	c.Buried via	NO
3	Via Details	
	a. Micro Via (Layer:1-2 AND Layer 1-6)	0.1mm / 0.2mm, 621 Nos
	b. Through hole	0.15 mm / 0.45mm, 804 Nos
	c.Approximate No of Via's	1425
4	No. of Copper layers	8
5	Substrate Material(Top)	RO3003, 10 mil
6	Preperg material	RO3003(10mil),FR4(5mil)
7	Board Size	52mm x 50mm
8	Minimum Track Width, Gap	
	Top layer	0.15mm,0.4mm
	Bottom and inner layers	0.15mm
9	Minimum gap	0.1mm
10	Board overall thickness tolerance	1.533mm +/- 10%
11	Solder mask	Top and bottom layer
12	Surface finish	ENIG
13	Copper thickness	17 microns
14	Solder mask color	no preference
15	Silk screen color	Top,White
16	ROHS compliance	required
17	Via on pad	No
18	Via filling	Yes
19	Edge plating	No
20	PCB type	Industrial grade
21	Fabrication file format	Gerber files RS-274X format
22	Impedance Control	Top Layer
23	Electrical testing	required
24	No of boards required	5
25	Fabrication lead time	30 days maximum

Stackup

Thickness in mm

Solder Mask		
Layer 1 – Copper		0.017
Substrate – RO3003		0.254
Layer 2 – Copper		0.017
Prepreg – RO3003		0.254
Layer 3 – Copper		0.017
Substrate – FR4		0.127
Layer 4 – Copper		0.017
Prepreg – FR4		0.127
Layer 5 – Copper		0.017
Substrate – FR4		0.127
Layer 6 – Copper		0.017
Prepreg – RO3003		0.254
Layer 7 – Copper		0.017
Substrate – RO3003		0.254
Layer 8 – Copper		0.017
Solder Mask		
Total		1.533

S No	Components Assembly	Quantity
1	Passives	
	SIZE-0402	81
	SIZE-0802	11
	SIZE-0603	4
	SIZE-3528	1
	SIZE-1608	11
2	BGA – 0.5mm pitch – 314 pins	1
3	MSOP-12	1
4	2.5 mm x 2 mm	1
5	WSON-8	1
6	TSSOP-20	1
7	Connector – 100 Pin SMD 0.5mm pitch	1

Note : 1. Gerber files will be supplied on request
2. All the components will be supplied